

Electronic Patent Application Fee Transmittal

| Application Number: | 09712749 | | | |
|--|---|----------|--------|----------------------|
| Filing Date: | 14-Nov-2000 | | | |
| Title of Invention: | LOW PROFILE INTEGRATED MODULE INTERCONNECTS AND METHOD OF FABRICATION | | | |
| First Named Inventor/Applicant Name: | Chia-Yu Fu | | | |
| Filer: | David George Dolezal/Dee Matocha | | | |
| Attorney Docket Number: | CT00-020 | | | |
| Filed as Large Entity | | | | |
| Utility under 35 USC 111(a) Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-----------------------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Request for continued examination | 1801 | 1 | 810 | 810 |
| Total in USD (\$) | | | | 810 |